

Declaration on the Restriction of Use of Certain Hazardous Substances in Electrical & Electronic Equipment

(RoHS 2 Directive 2011/65/EU as modified by 2015/863/EU)

Product / Assembly Name:	nShield Connect XC & Connect XC Serial Console
Product / Assembly Model:	NH2075 & NH2089
Marketing Number:	NH2075-x ¹ & NH2089-x ¹

Note 1 - where x can be any alphanumeric character or blank and denotes marketing / software variations

Entrust uses commercially reasonable efforts to ensure compliance with RoHS regulation by our supply chain. In reliance on the responses that we have received and data that we have obtained from our suppliers as well as information obtained through our own audit program, Entrust certifies that, to the best of our knowledge and belief the above listed products are manufactured in compliance with the Restriction of Hazardous Substances (RoHS), Directive 2011/65/EU as modified by 2015/863/EU and does not contain any of the hazardous substances listed in the table below in concentrations above the legal limits defined.

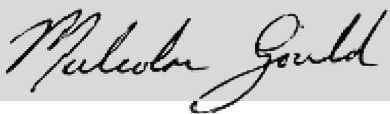
Where a specific application is exempted from restriction, a valid and current exemption may have been used to demonstrate compliance (as defined in annex III of 2011/65/EU; see the next page for details).

Maximum concentration values tolerated by weight in homogeneous materials:

(Excluding materials and parts covered by a valid and current RoHS exemption - See Annex)

Lead (0,1%)	Polybrominated diphenyl ethers (PBDE) (0,1%)	Cadmium (0,01%)	Hexavalent chromium (0,1 %)	Polybrominated biphenyls (PBB) (0,1 %)
Mercury (0,1%)	Bis (2-ethylhexyl) phthalate (DEHP) (0.1%)	Butyl benzyl phthalate (BBP) (0.1%)	Dibutyl phthalate (DBP) (0.1 %)	Diisobutyl phthalate (DIBP) (0.1 %)

Declaration for and on behalf of Entrust Security UK Limited (Formerly nCipher Security Limited)

Name & Function:	Malcolm Gould	Regulatory Compliance Officer
Signature & Date:		15 th December 2025

Entrust Security UK Limited
Registered Office: One Station Square,
Cambridge, CB1 2GA, United Kingdom
Registered in England No. 11673268

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Annex

This declaration is based in part on information provided to Entrust by its suppliers. The RoHS Directive restricts the use of certain substances in electronic products; including certain allowable exemptions as defined in Annex III of 2011/65/EU.

- ☐ Item(s) does not contain RoHS restricted substances per the definition above
- ☐ Item(s) contains RoHS restricted substances above the limits per the definition above, except for lead in solder and selected exemptions, if any
- ☒ Item(s) does not contain RoHS restricted substances per the definition above, except for selected exemptions
- ☐ Item(s) is obsolete, no information is available
- ☐ Item(s) is unknown, no information is available

Extract from the RoHS Exemption List, Directive 2011/65/EU Annex III:

- ☐ 6(a) Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight.
- ☐ 6(a)-I Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight
- ☐ 6(b) Lead as an alloying element in aluminium containing up to 0,4 % lead by weight.
- ☒ 6(c) Copper alloy containing up to 4 % lead by weight.
- ☒ 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
- ☐ 7(b) Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission, and network management for telecommunications.
- ☒ 7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.
- ☐ 7(c)-II Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher.
- ☐ 7(c)-III Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC.
- ☐ 7(c)-IV Lead in PZT based dielectric ceramic materials for capacitors which are part of integrated circuits or discrete semiconductors.